

Method of Resin-Seal-Molding Electronic Component and Apparatus Therefor

ABSTRACT OF THE DISCLOSURE

A mold (110) for resin-seal-molding an electronic component is constituted by a first mold (111) and a second mold (112). At a mold face (PL face) of the molds, a substrate supply-set surface (113) having a flat shape without a step is provided. A pot
5 block (140) is joined with and separated from a side position (110a) of the mold (110) intersecting perpendicularly with the mold face (PL face) of the molds. In a state where the mold face and the pot block (140) are joined, a molten resin material in the pot block (140) is injected into a cavity (114). The overall structure of the mold (110) for resin-seal-molding an electronic component mounted on the substrate (400) is
10 simplified. Additionally, when resin-seal-molding the electronic component, a problem of variation in the thicknesses of the substrates (400) is solved. Thus, resin flash formation on the substrate surface is prevented.

Fig 10